

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

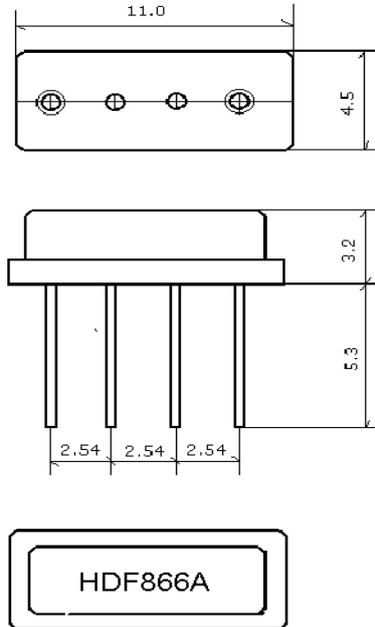
CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF866AF11 _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ DATE 日期: _____ 2004-10-7 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension

Unit:mm



2. Marking HD F866A

- 2.1 Color: Black or Blue
- 2.2 866.: Center Frequency(MHz)

3.Performance

3.1Application

Low-Loss SAW Filter of cordless system.

Center Frequency:866 MHz

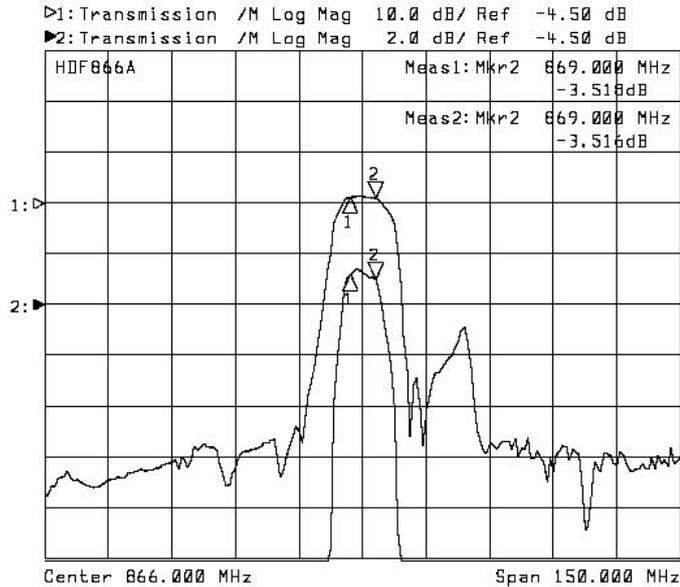
3.2Maximum Rating

Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-45°C to +85°C
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	11dBm

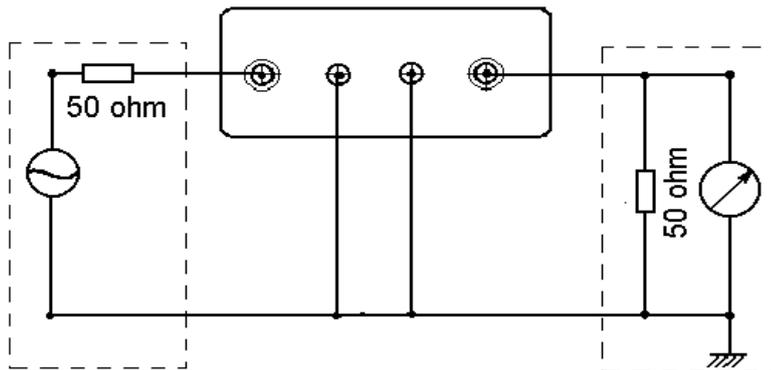
3.3 Electronic Characteristics

Item	Frequency	Specification
Center Frequency(fo)	866MHz	
Insertion Loss	Fo ± 2.0MHz	4.5dB max.
Stop Band Rejection	Fo-400~-40.8MHz	47dB min.
	Fo+50~+400MHz	47dB min.
Terminating Impedance		50 Ω // <10nH

3.4 Frequency Characteristics



3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.3.

4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.3.

4-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.3.

4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 3.3.

4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered . Please avoid soldering another part of component.